

# Fast Moving Consumer Electronics

Ritemp advances in-mould cooling for both simple and complex part geometries. This improves cycle times, crystallization and dimensional stability of each part in single and multi-impression moulds. The result is improved part quality and higher yield in assembly processes.

Less mould maintenance is required, water hoses are reduced, and investment in external water heaters is not required.

The Ritemp cooling system design means mould bases can be standardized for rapid mould manufacture.



## challenge

Cycle time reduction, and rapid mould manufacture, for hand held devices

## current mould/ part characteristics

Conventional: . . . . .2 cavity  
Current Cycle Time: . . . . .8.8 sec

## part details

Weight: . . . . .7.50 g  
Nominal Thickness: . . . . .0.8mm  
Maximum Thickness: . . . . .0.8mm  
Material: . . . . .ABS/PC blend

## evaluation

1. Part analysis used to determine optimal curing time using Ritemp
2. Projected NEW cycle time reduction of 4.5 seconds
3. Ability to cool through lifters

## Ritemp™ benefits

-  51% reduction in cycle time
-  4.5 second per cycle savings
-  Faster start ups
-  Improved gate cooling

## challenge

To improve cycle times and individual impression part quality, to increase part yield to match mould production requirements

## current mould/ part characteristics

Conventional: . . . . .4 cavity  
Current Cycle Time: . . . . .Confidential






## part details

Weight: . . . . .20.0 g  
Nominal Thickness: . . . . .2.4mm  
Material: . . . . .PETG 15% GR

## evaluation

1. Part analysis used to determine optimal curing time using Ritemp
2. Projected NEW cycle time reduction greater than 20%
3. New stack design by Ritemp

## Ritemp™ benefits

-  Tolerance CPK improved 40%
-  Greater than 20% reduction in cycle time
-  Cooled with 3 GPM's per mould half
-  standardisation of moulds
-  reduced maintenance insert life improved